





IN THE CLAIMS:

Please amend claims 61 and 64 so that claims 61-64 read as follows:

- Sub C*
61. (Amended) A socket for releasably connecting a first electronic component to a second electronic component, comprising:
- a first plurality of resilient contact structures extending from a surface of a support substrate, the first plurality of resilient contact structures configured to make electrical connections with a plurality of bond pads on the first electronic component;
 - a second plurality of resilient contact structures extending from the surface of the support substrate, the second plurality of resilient contact structures configured to make electrical connections with a plurality of special contact pads on the first electronic component, wherein said special contact pads are smaller than said bond pads; and
 - a plurality of contact structures disposed on another surface of the support substrate for making electrical contact with said second electronic component, ones of the contact structures are connected to ones of the first plurality of resilient contact structures, and ones of the contact structures are connected to ones of the second plurality of resilient contact structures.
62. The socket of claim 61, wherein the second electronic component is a circuit board.
63. The socket of claim 61, further comprising means for receiving the first electronic component.
- B2* *4* 64. (Amended) The socket of claim ~~61~~, further comprising means for urging the first electronic component down onto the first and second resilient contact structures.



 Please add new claims 65-80 as follows:

 (New) The socket of claim , wherein said first electronic component is an integrated circuit.

 (New) The socket of claim , wherein said first electronic component comprises:
a plurality of first input/output buffers each electrically connected to one of said bond pads; and



a plurality of second input/output buffers each electrically connected to one of said special contact pads,



wherein each of said second input/output buffers is smaller than each of said first input/output buffers.

 (New) The socket of claim , wherein said first electronic component comprises:
a plurality of first electrostatic discharge protection circuits each electrically connected to one of said bond pads; and

a plurality of second electrostatic discharge protection circuits each electrically connected to one of said special contact pads,

wherein each of said second electrostatic discharge protection circuits is smaller than each of said first electrostatic discharge protection circuits.

 (New) The socket of claim , wherein a height from a surface of said first electronic component of each of said special contact pads is less than a height from said surface of each of said bond pads.

 (New) The socket of claim , wherein said second plurality of resilient contact structures extend farther from said top surface of said support substrate than said second plurality of resilient contact structures.

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~~70.~~ (New) The socket of claim ~~60~~⁹, wherein an amount by which said second plurality of resilient contact structures extend farther from said top surface of said support substrate than said second plurality of resilient contact structures corresponds to an amount by which said height from said surface of said first electronic component of each of said special contact pads is less than said height from said surface of each of said bond pads.

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~~71.~~ (New) The socket of claim ~~61~~¹, wherein each of said first plurality of resilient contact structures comprises a blade tip.

Sub C2
72. (Amended) A socket comprising:
a substrate;
a first plurality of resilient contact means for making electrical connections between terminals on a first surface of said substrate and bond pads on a first electronic component;
a second plurality of resilient contact means for making electrical connections between terminals on said first surface of said substrate and special contact pads on said first electronic component, wherein said special contact pads are smaller than said bond pads;
a third plurality of contact means for making electrical connections between terminals on a second surface of said substrate and a second electronic component;
means for electrically connecting ones of said first plurality of contact means with ones of said third plurality of contact means;
means for electrically connecting ones of said second plurality of contact means with ones of said third plurality of contact means; and
means for urging said first electronic component against said first plurality of resilient contact means and said second plurality of resilient contact means.

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~~73.~~ (New) The socket of claim ~~72~~¹², wherein the second electronic component is a circuit board.

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~~74.~~ (New) The socket of claim ~~72~~¹², wherein said first electronic component is an integrated circuit.

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~~75.~~ (New) The socket of claim ~~72~~¹², wherein said first electronic component comprises:
a plurality of first buffer means for buffering signals through each of said bond pads; and

a plurality of second buffer means for buffering signals through each of said special contact pads,

wherein each of said second buffer means is smaller than each of said first buffer means.

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~~76.~~ (New) The socket of claim ~~72~~¹², wherein said first electronic component comprises:
a plurality of first protection means for protecting said first electronic component from electrostatic discharge through each of said bond pads; and

a plurality of second protection means for protecting said first electronic component from electrostatic discharge through each of said special contact pads,

wherein each of said second protection means is smaller than each of said first protection means.

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~~77.~~ (New) The socket of claim ~~72~~¹², wherein a height from a surface of said first electronic component of each of said special contact pads is less than a height from said surface of each of said bond pads.

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~~78.~~ (New) The socket of claim ~~77~~¹⁷, wherein said each of said second plurality of resilient contact means extends farther from said surface of said support substrate than each of said second plurality of resilient contact means.

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~~79~~. (New) The socket of claim ¹⁸~~78~~, wherein an amount by which each of said second plurality of resilient contact means extends farther from said surface of said support substrate than each of said second plurality of resilient contact means corresponds to an amount by which said height from said surface of said first electronic component of each of said special contact pads is less than said height from said surface of each of said bond pads.

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~~80~~. (New) The socket of claim ¹²~~72~~, wherein each of said first plurality of resilient contact means comprises a blade tip.
